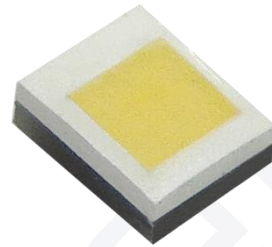


# 5F1519AW3FFNZQNG

- ◆ Outline : 1.5\*1.9\*0.8mm
- ◆ High Power Output And High efficiency
- ◆ Good thermal dissipation & Optical uniformity



## Table of Contents:

Features-----	1
Product Code-----	2
Typical Product Characteristics-----	3
Maximum Rating-----	4
Luminous Intensity Binning-----	5
Forward Voltage Binning-----	5
Color Coordinate Binning-----	6
Relative Spectral Power Distribution-----	7
Typical Diagram Characteristics of Radiation-----	7
Electronic-Optical Characteristics-----	8
Thermal Design for De-rating-----	9
Dimensions-----	10
Suggest Stencil Pattern-----	10
Packaging-----	11
Reflow profile-----	13
Precautions-----	14
Test items and results of reliability-----	16

## Features

- RoHS and REACH-compliant
- MSL2 qualified according to JEDEC J-STD 020
- ESD 8KV (HBM: ANSI/JEDEC JS-001 Class 3B)
- AEC-Q102 Qualified

## Applications

- Automotive Exterior Lighting

■ Product Code

**5 – F – 1519 – A – W3FF – N – Z – Q – N – G**

① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩

①	②	③	④	⑤
<b>Process type</b>	<b>Category</b>	<b>Specification</b>	<b>Lens Angle code</b>	<b>Dice wavelength &amp; Luminous rank</b>
5:For Automotive	F: Flip Chip LED	1519: 1.5*1.9mm	A : 120°	W3xx: Cool White

⑥	⑦	⑧	⑨	⑩
<b>Support code</b>	<b>Zener &amp; High CRI</b>	<b>Cap color code</b>	<b>Module &amp; Lens code</b>	<b>Current code</b>
N: AlN	Z: Zener	Q: 6000K	N: Paintings	G: 500mA for test

**■ Typical Product Characteristics(Ta=25°C)**

Item	Symbol	Value			Unite	Test Condition
		Min.	Typ.	Max.		
<b>Forward Voltage<sup>1</sup></b>	V <sub>F</sub>	2.8		3.4	V	I <sub>F</sub> =500mA
<b>Reverse Current</b>	I <sub>R</sub>			10	μA	V <sub>R</sub> =5V
<b>Luminous Intensity<sup>2</sup></b>	Φ	170		230	lm	I <sub>F</sub> =500mA
<b>Viewing Angle<sup>3</sup></b>	2θ <sub>1/2</sub>		120		deg	I <sub>F</sub> =500mA
<b>Correlated Color Temperature</b>	CCT	5400	6000	6700	K	I <sub>F</sub> =500mA

Notes:

1. The above forward voltage measurement allowance tolerance is ±0.05V
2. The above luminous flux measurement allowance tolerance ±7%
3. The above Viewing angle (2θ<sub>1/2</sub>) measurement allowance tolerance ±10°
4. IS standard test.

**■ Maximum Rating (Ta =25°C)**

Characteristics	Symbol	Min.	Typ.	Max.	Unit
<b>DC Forward Current<sup>1</sup></b>	I <sub>F</sub>			1500	mA
<b>Pulse Forward Current<sup>2</sup></b>	I <sub>PF</sub>			3000	mA
<b>Reverse Voltage</b>	V <sub>R</sub>			5	V
<b>Junction Temperature<sup>3</sup></b>	T <sub>J</sub>			150	°C
<b>Thermal Resistance Junction/ Solder Point</b>	R <sub>THJ-S</sub>		4		°C/W
<b>Operating Temperature Range</b>	T <sub>OPR</sub>	-40	–	125	°C
<b>Storage Temperature Range</b>	T <sub>STG</sub>	-40	–	125	°C
<b>Soldering Temperature</b>	T <sub>SD</sub>			260	°C

**Notes:**

1. For other ambient, limited setting of current will depend on de-rating curves.
2. Duty 1/10, pulse width 0.1ms
3. When drive on maximum current , T<sub>J</sub> must be kept below 150°C

**■ Luminous Intensity Binning (IF=500mA)**


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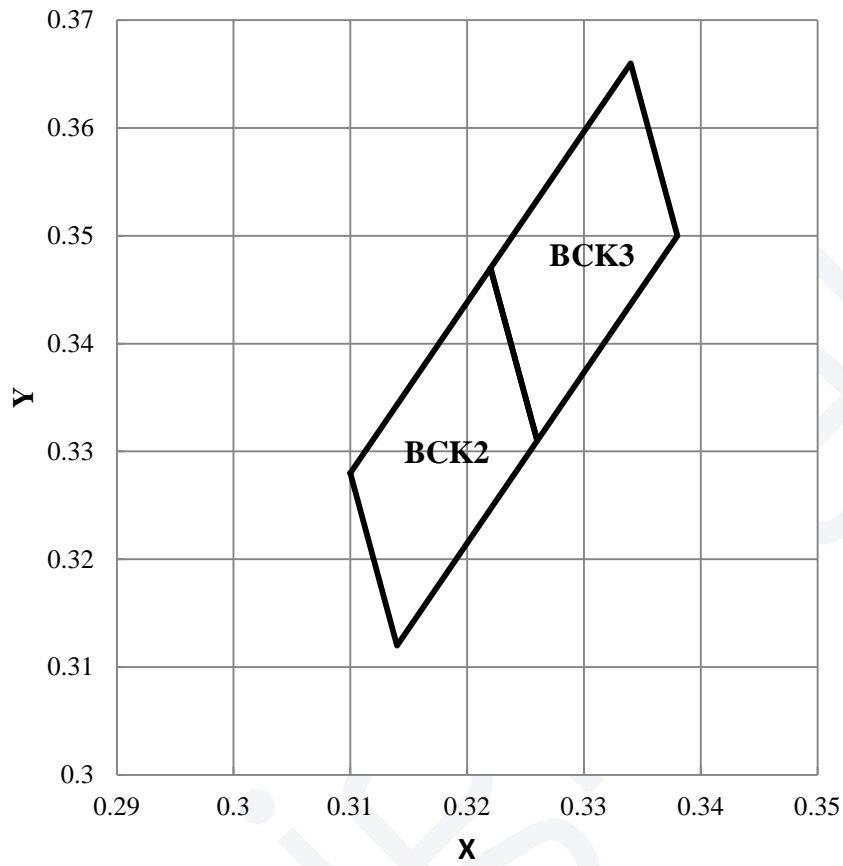
Bin Code	Min. $\Phi_v$ (Lm)	Max. $\Phi_v$ (Lm)
30	170	200
31	200	230

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**■ Forward Voltage Binning (IF=500mA)**


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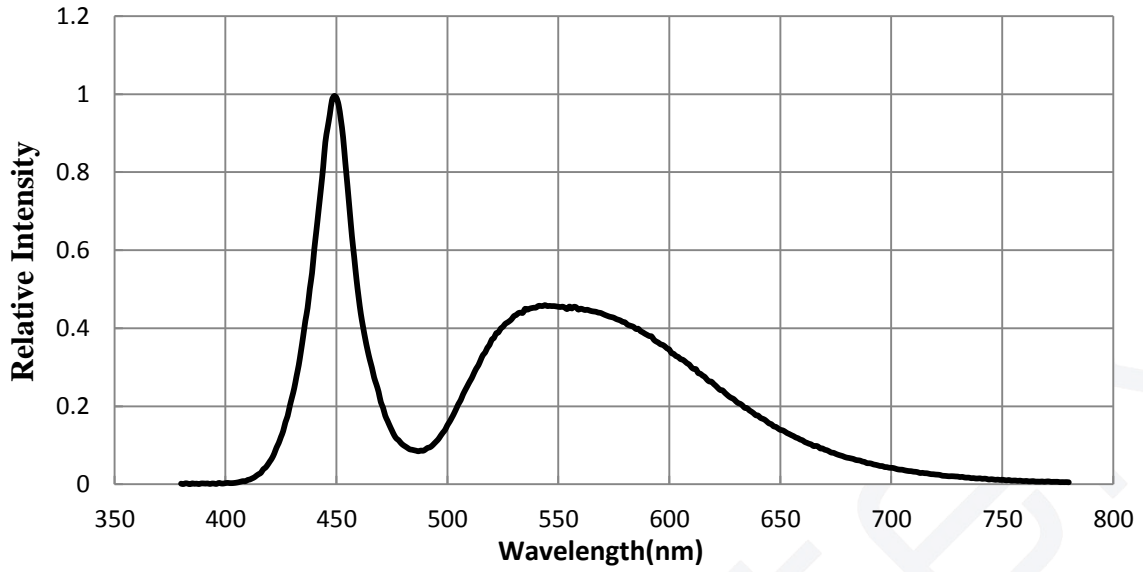
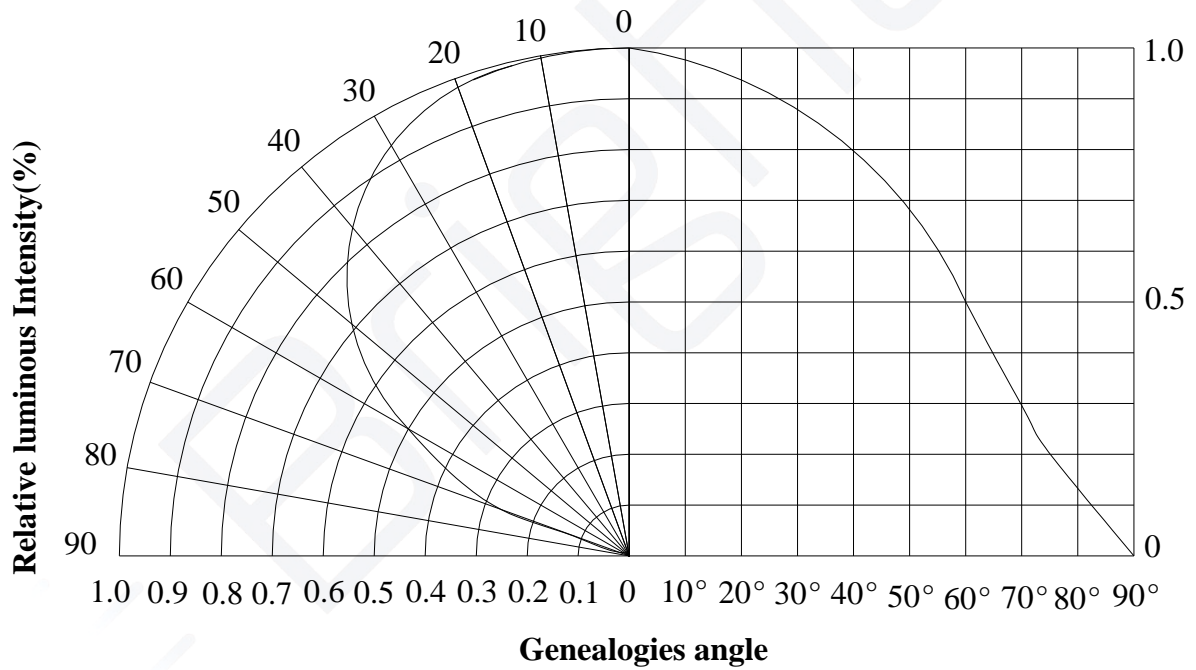
Bin Code	Min. $V_F$ (V)	Max. $V_F$ (V)
L	2.8	3.0
M	3.0	3.2
N	3.2	3.4

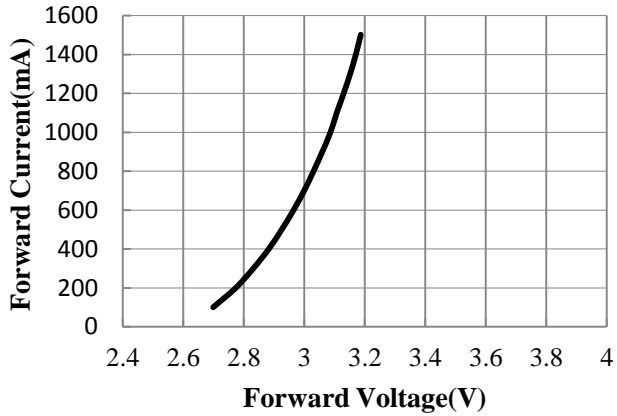
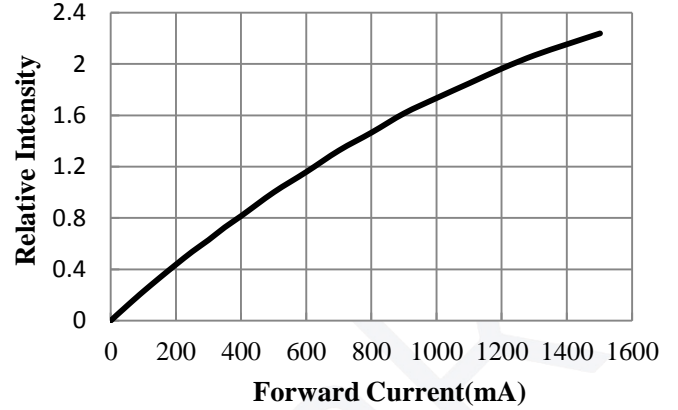
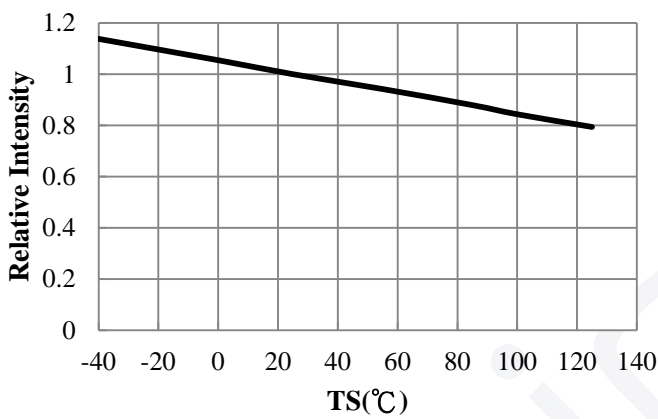
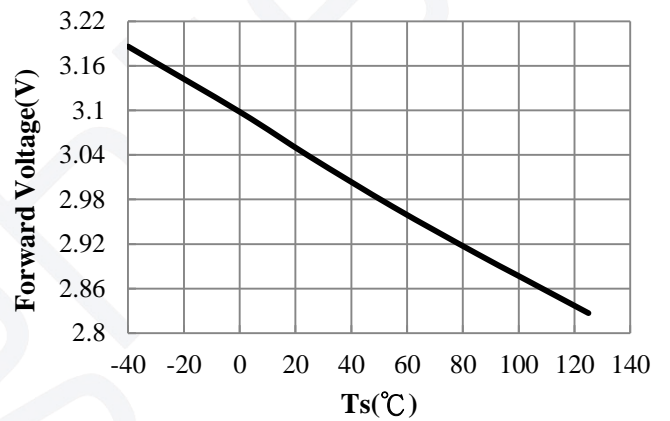
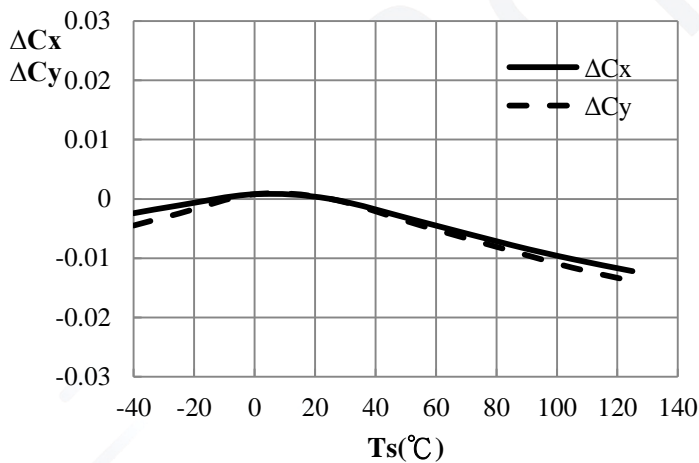
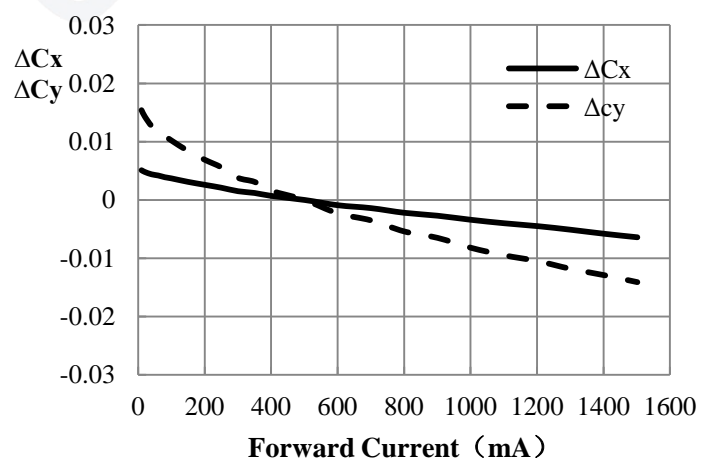
**Color Coordinate Binning (IF=500mA)**


BIN	CIE X	CIE Y	BIN	CIE X	CIE Y
<b>BCK2</b>	0.3100	0.3280	<b>BCK3</b>	0.3220	0.3470
	0.3140	0.3120		0.3260	0.3310
	0.3260	0.3310		0.3380	0.3500
	0.3220	0.3470		0.3340	0.3660

Notes:

The above color coordinates (CIE x, CIE y) measurement allowance tolerance is  $\pm 0.007$

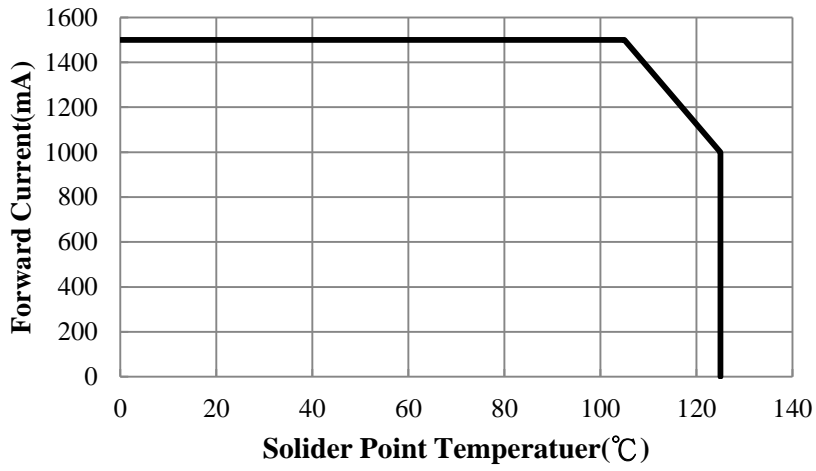
**■ Relative Spectral Power Distribution**

**■ Typical Diagram Characteristics of Radiation**


**Electronic-Optical Characteristics**
**Forward Current vs. Forward Voltage**

**Relative Intensity vs. Forward Current**

**Relative Luminous Flux vs. Solider Temperature**

**Forward Voltage vs. Solider Temperature**

**Chromaticity Coordinate Shift vs. Solider Temperature**

**Chromaticity Coordinate Shift vs. Forward Current**


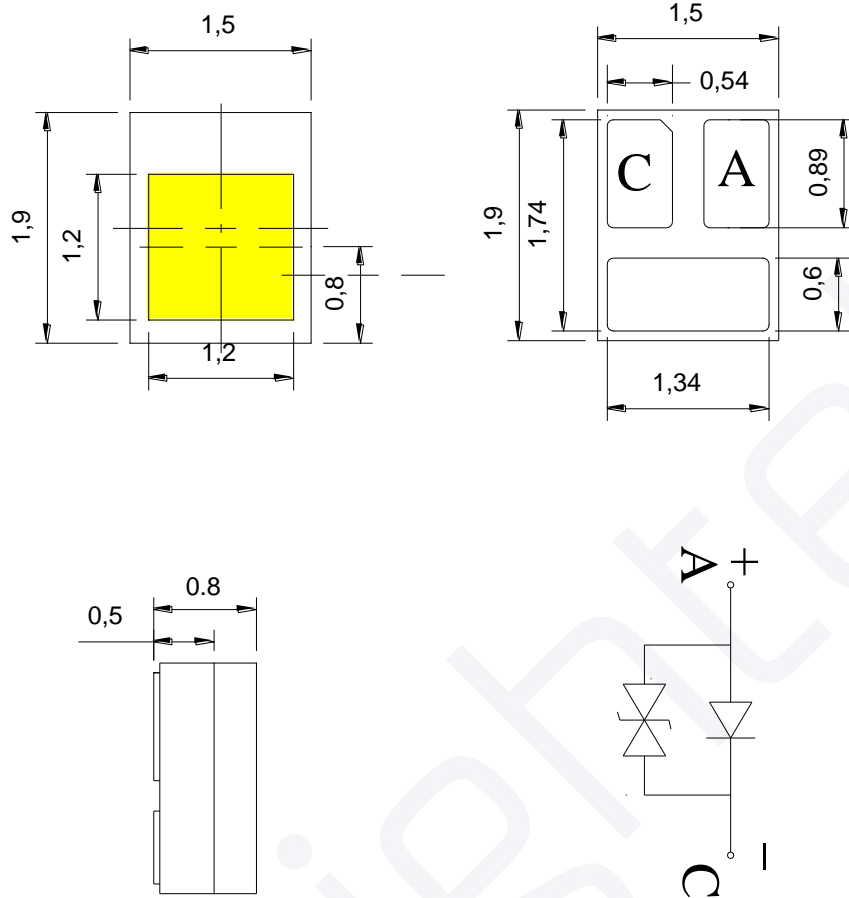


## ■ Thermal Design for De-rating

The maximum forward current is determined by the thermal resistance between the LED junction and solder point. It is crucial for the end product to be designed in a manner that minimizes the thermal resistance from the solder point to ambient in order to optimize lamp life and optical characteristics.

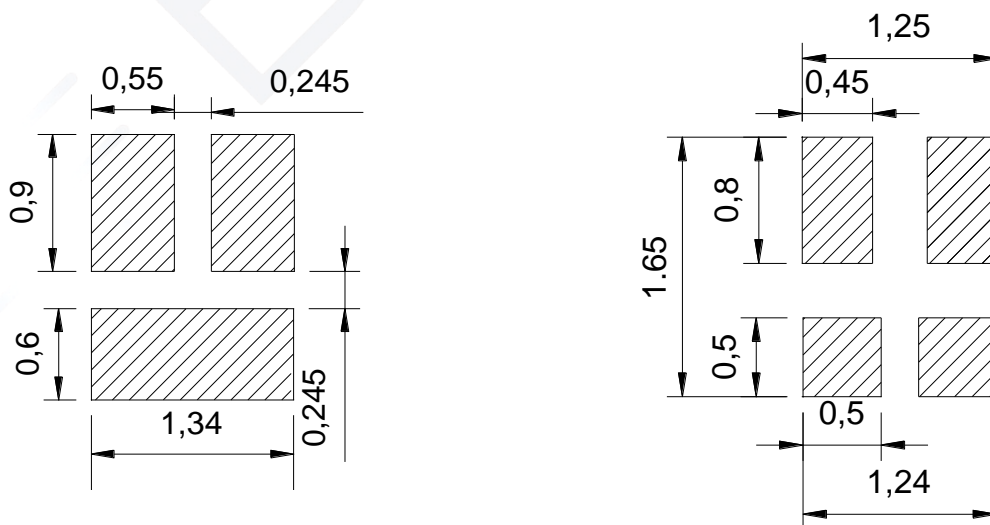


■ Dimensions



§ All dimensions are in millimeters.  
 § Tolerance is  $\pm 0.13$ mm unless other specified.

■ Suggest Stencil Pattern (Recommendations for reference)



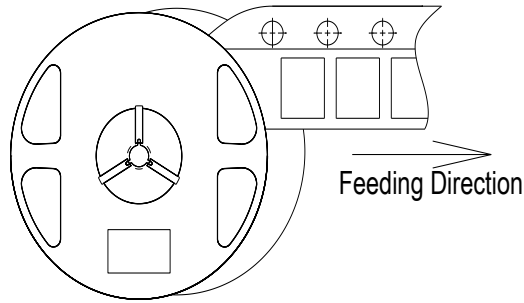
RECOMMENDED PCB SOLDER PAD

RECOMMENDED STENCIL PATTERN  
(HATCHED AREA IS OPENING)

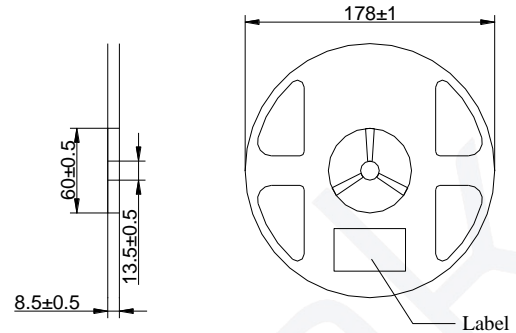
§ Suggest stencil  $t = 0.12$  mm

■ Packaging

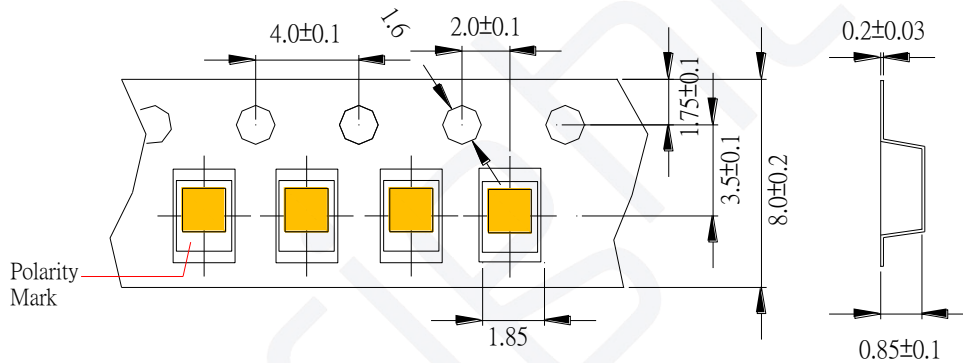
● Feeding Direction (Unit: mm)



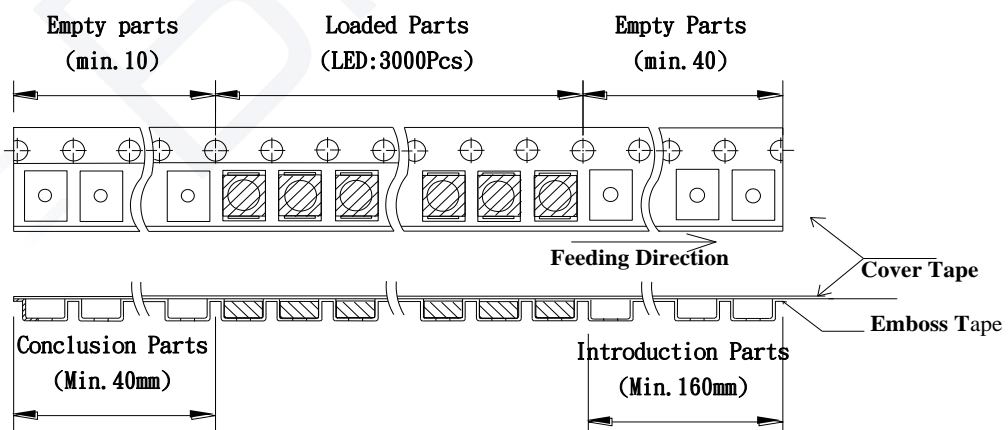
● Dimensions of Reel (Unit: mm)



● Dimensions of Tape (Unit: mm)

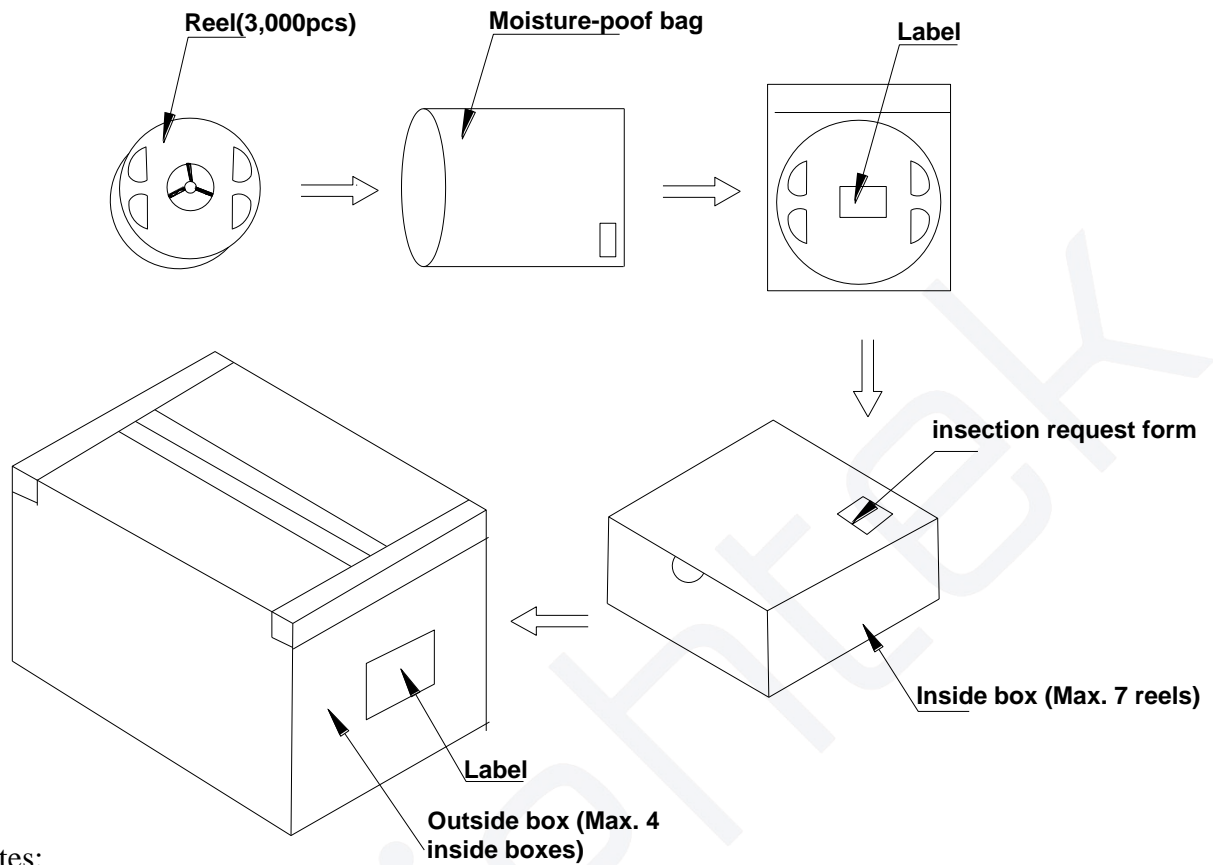


● Arrangement of Tape



Notes:

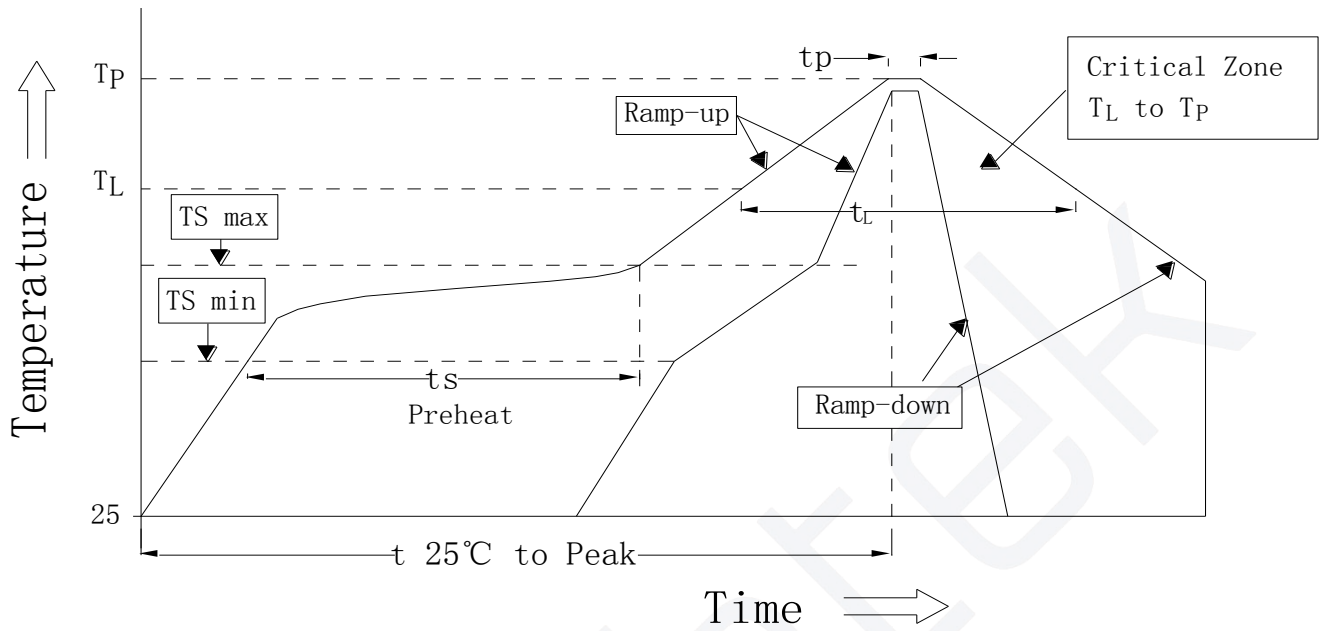
1. Empty component pockets are sealed with top cover tape
2. The max loss number of SMD is 2pcs;
3. The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications;
4. 3,000pcs per reel;
5. The remainder packing in multiples of 500pcs.

**■ Packaging**

**Notes:**

Reeled product (max.3,000) is packed in a sealed moisture-proof bag. Seven bags are packed in an inner box (size: about 260 X 230 X 100 mm) and four inner boxes are in an outer box (size: about 480 X 275 X 215 mm). On the label of moisture-pooof bag, there should be the information of Part No., Lot No. and quantity number; also the total quantity number should be on inspection request form on outer box.

■ Reflow Profile

SMT Reflow Soldering Profile



Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Min.	Recommendation	Max.	
Ramp-up rate to preheat (25°C to 150°C)			2	3	K/s
Time $t_s$ ( $T_{S\ min}$ to $T_{S\ max}$ )	$t_s$	60	100	120	s
Ramp-up rate to peak ( $T_{S\ max}$ to $T_P$ )			2	3	K/s
Liquidus temperature	$T_L$		217		°C
Time above liquidus temperature	$t_L$		80	100	s
Peak temperature	$T_P$		245	260	°C
Time within 5 °C of the specified peak temperature $T_P - 5\ K$	$t_p$	10	20	30	s
Ramp-down Rate ( $T_P$ to 100 °C)			3	4	K/s
Time 25 °C to $T_P$				480	s

Notes:

1. Do not stress the silicone resin while it is exposed to high temperature.
2. The reflow process should not exceed 2 times.

■ **Precautions**

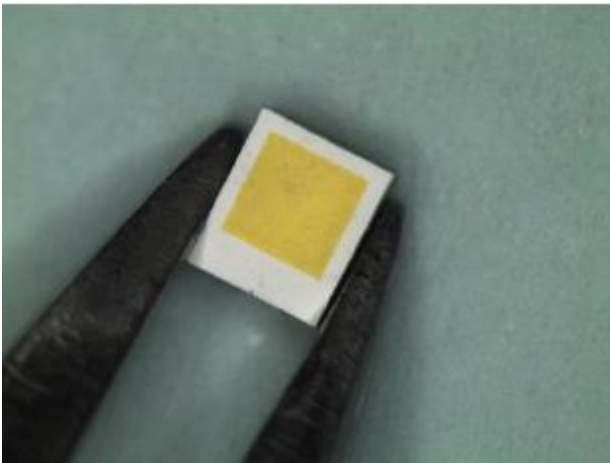

1. Recommendation for using LEDs

- 1.1 The lens of LEDs should not be exposed to dust or debris. Excessive dust and debris may cause a drastic decrease in the luminosity.
- 1.2 Avoid mechanical stress on LED lens.
- 1.3 Do not touch the LED lens surface. It would affect the optical performance of the LED due to the LED lens' damage.
- 1.4 Pick & place tools are recommended for the remove of LEDs from the factory tape & reel packaging

2. Lens handling

Please follow the guideline to pick LEDs.

- 2.1 Use tweezers to pick LEDs.
- 2.2 Do not touch the lens by using tweezers.
- 2.3 Do not touch lens with fingers.
- 2.4 Do not apply more than 4N (400gw) directly onto the lens.

Correct ( ✓ )	Wrong ( X )
	

3. Lens cleaning

In the case which a small amount of dirt and dust particles remain on the lens surface, a suitable cleaning solution can be applied.

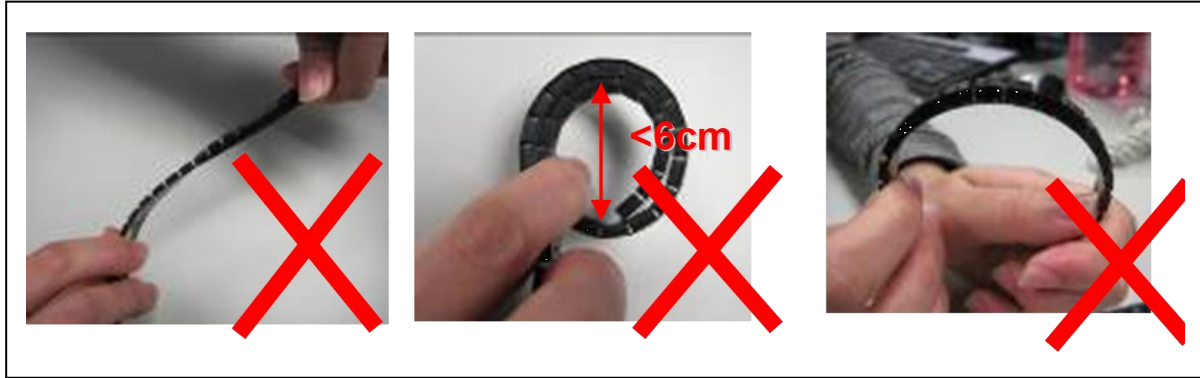
- 3.1 Try a gentle wiping with dust-free cloth.
- 3.2 If needed, use dust-free cloth and isopropyl alcohol to gently clean the dirt from the lens surface.
- 3.3 Do not use other solvents as they may directly react with the LED assembly.
- 3.4 Do not use ultrasonic cleaning which will damage the LEDs.

4. Carrier tape handling

The following items are recommended when handling the carrier tape of LEDs.

- 4.1 Do not twist the carrier tape.
- 4.2 The inward bending diameter should not be smaller than 6cm for each carrier tape.

#### 4.3 Do not bend the tape outward.



#### 5. Storage

##### 5.1 The moisture-proof bag is sealed :

The LEDs should be stored at 30°C or less and 90%RH or less. And the LEDs are limited to use within one year, while the LEDs is packed in moisture-proof package with the desiccants inside.

##### 5.2 The moisture-proof bag is opened :

The LEDs should be stored at 30°C or less and 60%RH or less. Moreover, the LEDs are limited to solder process within 168hrs. If the humidity indicator card shows the pink color in 10% even higher or exceed the storage limiting time since opened, that we recommended to baking LEDs at 60°C at least 24hrs. To seal the remainder LEDs return to the moisture-proof bag, it's recommended to be with workable desiccants.

**■ Test Items and Results of Reliability**

Test Item	Test Conditions	Duration/ Cycle	Number of Damage	Reference
Thermal Shock	-40°C 30min ↑↓5min 125°C 30min	1000 cycles	0/26	JESD22 A-104
High Temperature Storage	T <sub>a</sub> =125°C	1000 hrs	0/26	JESD22 A-103B
Low Temperature Storage	T <sub>a</sub> =-40°C	1000 hrs	0/26	JESD22 A-119
Life Test	T <sub>a</sub> =25°C I <sub>f</sub> =1500mA	1000 hrs	0/26	JESD22 A-108
High Humidity Heat Operation	85°C RH=85% I <sub>f</sub> =1000mA	1000 hrs	0/26	JESD22 A-101
High Temperature Operation	T <sub>a</sub> =105°C I <sub>f</sub> =1000mA	1000 hrs	0/26	JESD22 A-108C
ESD(HBM)	2KV at 1.5kΩ;100pF	3 times	0/30	ANSI/JEDEC JS-001

Failure Criteria				
Item	Symbol	Condition	Criteria for Judgment	
			Min	Max
Forward Voltage	V <sub>F</sub>	I <sub>f</sub> =1000mA	-	USL <sup>1</sup> ×1.1
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	-	10μA
Radiant Power	P <sub>O</sub>	I <sub>f</sub> =1000mA	LSL <sup>2</sup> ×0.7	-

**Notes**

1. USL: Upper specification level
2. LSL: Lower specification level